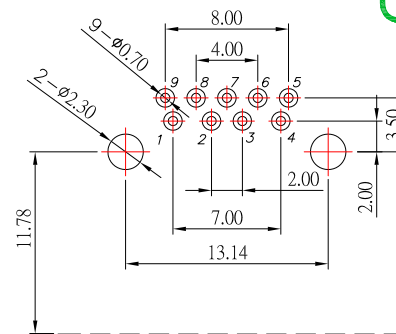
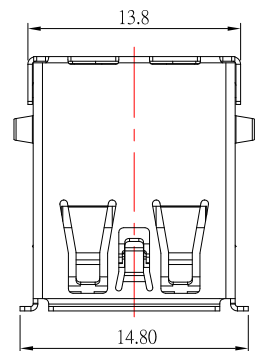




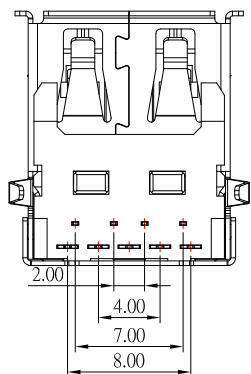
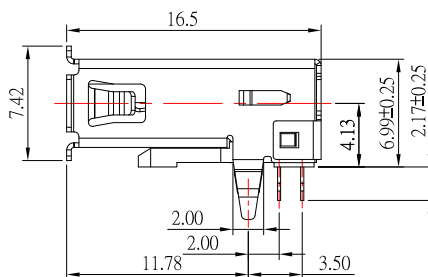
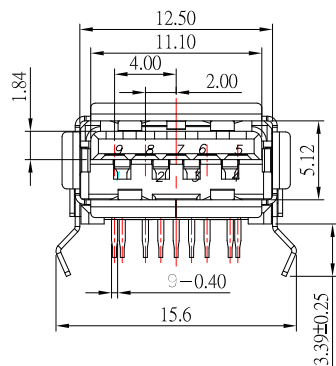
SUA-110H7C-32x-S277

鍍層厚度：

Blank	: 1u"
2	: 15u"
3	: 30u"



RECOMMENDED PCB LAYOUT TOP VIEW



NOTE:

1.MATERIAL:

- 1.1 Housing: LCP
- 1.2 Contact: 5Pin:Brass ; 4Pin:Phosphor Bronze
- 1.3 Shell: SUS

2.Finish:

- 2.1 Contact: Plated Gold in Mating Area ;
Tin Plated on Solder Balls ;
Nickel under plated overall
- 2.2 Shell: Nickel under Plated surface layer

3.SPECIFICATION:

- 3.1 Rating: 1.8A
- 3.2 Insulator Resistance:100MΩ Min
- 3.3 Dielectric Strength: 100V AC
- 3.4 Contact Resistance: 30mΩ Max
- 3.5 Operation Temperature: -40°C ~ +85°C

CONTACT 建倚科技股份有限公司
CONTACT TECHNOLOGY CORP.

TOLERANCE UNLESS OTHERWISE STATED :

Up to 5	±0.2
Above 5 ~ 15	±0.3
Above 15 ~ 30	±0.4
Above 30 ~ 50	±0.5
Angle	±0.3°

3RD. ANGEL'S



UNITS MM

DRAWN BY:	DATE	MAT'L	TITLE	CONNECTOR
Jack Lu	08/10/23			
CHECKED BY:	DATE	FINISH	MODLE	USB AF 3.1 插板 捲邊 膠芯正向 外殼彎脚
Jacky Chen	08/10/23			H6.99mm L16.5mm GEN 2
APPROVED BY:	DATE	SCALE	DWG NO.	SUA-110H7C-32x-S277
Tony Kao	08/10/23	1 : 1	PART NO.	SUA-110H7C-32x-S277
		SHEET NO.	1 of 1	
			SIZE	A4
			VER	R

ITEM NO.	DESCRIPTION	DRAWN	DATE